



**PATENT APPLICATION**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Hideyuki Kurita et al.

Group Art Unit: 2827

Application No.: 09/640,862

Examiner: I. Patel

Filed: August 18, 2000

Docket No.: 107082

For: PROCESSES FOR MANUFACTURING FLEXIBLE WIRING BOARD AND THE  
RESULTING FLEXIBLE WIRING BOARD

**AMENDMENT UNDER 37 C.F.R. §1.111**

Director of the U.S. Patent and Trademark Office  
Washington, D.C. 20231

Sir:

In reply to the October 2, 2002, Office Action, the period for response being extended by the attached Petition for Extension of Time, please amend the above-identified application as follows:

**IN THE CLAIMS:**

Please replace claim 14 as follows:

14. (Three Times Amended) A flexible wiring board comprising a plurality of patterned metal films with a resin film being interposed therebetween, among which at least adjacent two patterned metal films are electrically connected to each other via bumps, one of said patterned metal film having at least one opening, wherein said resin film is thermally shrinkable to discharge moisture through at least one opening of said patterned metal film.